

TOSHIBA

TLN101A

TOSHIBA INFRARED LED GaAs INFRARED EMITTER

TLN101A

INFRARED LED FOR PHOTO SENSOR

OPTO-ELECTRONIC SWITCH

SMOKE SENSOR

INFRARED RAYS APPLIED EQUIPMENT

ROTARY ENCODER

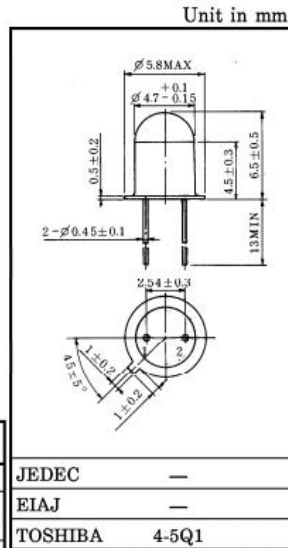
LINEAR SCALE

- Excellent linearity of radiant power and modulation by pulse operation and high frequency is possible.
- Highly reliable because of hermetic seal.
- The same external shape as Photo Transistors TPS601A and TPS604.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current	I _F	100	mA
Forward Current Derating (Ta > 25°C)	ΔI _F / °C	-1	mA / °C
Pulse Forward Current (Note)	I _{FP}	1	A
Reverse Voltage	V _R	5	V
Operating Temperature Range	T _{opr}	-40~125	°C
Storage Temperature Range	T _{stg}	-55~150	°C

(Note) Pulse Width ≤ 100μs, Repetitive Frequency = 100Hz



Weight : 0.39g (TYP.)

PIN CONNECTION

1 ○ — 2

1. ANODE
2. CATHODE (CASE)

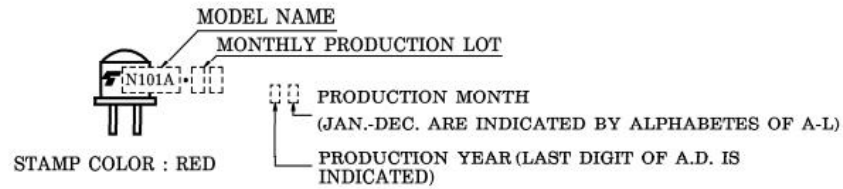
OPTO-ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V _F	I _F = 50mA	—	1.3	1.4	V
Pulse Forward Voltage	V _{FP}	I _{FP} = 1A	—	2.4	—	V
Reverse Current	I _R	V _R = 5V	—	—	10	μA
Radiant Intensity	I _E	I _F = 50mA	—	15	—	mW / sr
Radiant Power	P _o	I _F = 50mA	—	1.5	—	mW
		TLN101A-C				
Capacitance	C _T	V _R = 0, f = 1MHz	—	30	—	pF
Peak Emission Wavelength	λ _P	I _F = 50mA	—	940	—	nm
Spectral Line Half Width	Δλ	I _F = 50mA	—	50	—	nm
Half Value Angle	θ _{1/2}	I _F = 50mA	—	±4	—	°

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- TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

PRODUCT INDICATION



PRECAUTION

Please be careful of the followings.

1. Soldering temperature : 260°C MAX.
Soldering time : 5s MAX.
(Soldering portion of lead : above 1.5mm from the body of the device)
2. If the lead is formed, the lead should be formed at a distance of 2mm from the body of the device.
Soldering shall be performed after lead forming.

